

40V N-Channel Trench MOSFET

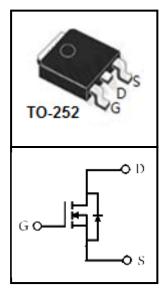
FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Hard switched and high frequency circuits





Device Marking and Package Information				
Device	Package	Marking		
CTD04N11P5	TO-252	CTD04N11P5		

Absolute Maximum Ratings at T _j = 25°C unless otherwise noted				
Parameter		Symbol Value		Unit
Drain-Source Voltage (V _{GS} = 0V)		V _{DSS}	40	V
Drain Current-Continuous(Tc =25°C)	(note1)	,	55	_
Drain Current-Continuous(Tc=100°C)	(note1)	I _D	30	Α
Pulsed Drain Current	(note2)	I _{DM}	100	А
Gate Source Voltage		V _{GSS}	±20	V
Single Pulse Avalanche Energy	(note3)	E _{AS}	31	mJ
Power Dissipation T _C = 25°C	(note4)	P _D	34.7	W
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55~150	∘C

Thermal Characteristics					
Parameter		Symbol	Value	Unit	
Thermal Resistance,Junction-Ambient	(note1)	$R_{\theta JA}$	62	°C/W	
Thermal Resistance,Junction-Ambient(t≤10s)	(note1)	$R_{\theta JA}$	25	°C/W	
Thermal Resistance, Junction-Case	(note1)	R _{eJC}	3.6	°C/W	



Electrical Characteristics T _j = 25°C unless otherwise specified							
Para materia		Total October 1981	Value			Unit	
Parameter Symi		ol Test Conditions		Тур.	Max.		
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V	
Zero Gate Voltage Drain Current		$V_{DS} = 32V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	uA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 32V, V_{GS} = 0V, T_{J} = 55^{\circ}C$			5		
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA	
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0	1.5	2.5	V	
Drain Source On Begintance (notes)	В	V _{GS} = 10V, I _D = 12A		9.5	11.5	mΩ	
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_{D} = 10A$		13.5	16.5	mΩ	
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0V,		1314		pF	
Output Capacitance	C _{oss}	$V_{DS} = 15V$,		120			
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		88			
Total Gate Charge (4.5V)	Q_g			10.7			
Gate-Source Charge	Q_{gs}	$V_{DS} = 20V, I_{D} = 12A,$ $V_{GS} = 4.5V$		3.3		nC	
Gate-Drain Charge	Q_{gd}	65 -		4.2			
Turn-on Delay Time	t _{d(on)}			8.6			
Turn-on Rise Time	t _r	$V_{DS} = 20V, I_{D} = 1A$		3.4		ns	
Turn-off Delay Time	t _{d(off)}	$V_{GS} = 10V, R_G = 3.3\Omega$		25			
Turn-off Fall Time	t _f			2.2			
Body Diode Characteristics							
Source-Drain Current(Body Diode)	I _{SD}				55	Α	
Pulsed Source-Drain Current(Body Diode)	I _{SDM}				100	А	
Body Diode Voltage	V_{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 5A$, $V_{GS} = 0V$			1.2	V	

Notes

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2. The data tested by pulsed , pulse width≤300us , duty cycle≤2%
- 3. The EAS data shows Max. rating . The test condition is VDD =25V,VGS =10V,L=0.1mH $\,$
- 4. The power dissipation is limited by 175°C junction temperature
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

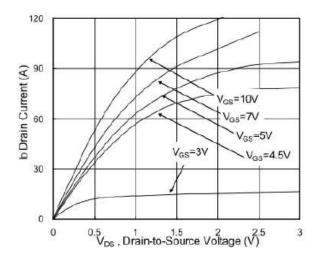


Fig.1 Typical Output Characteristics

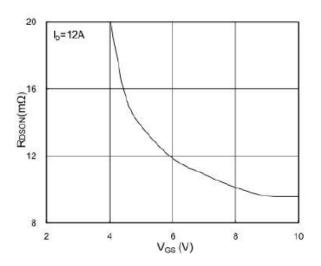


Fig.2 On-Resistance vs. G-S Voltage

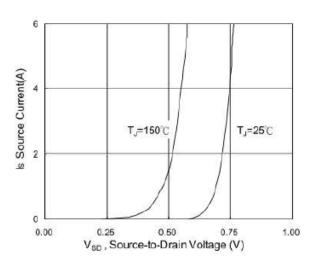


Fig.3 Forward Characteristics of Reverse Diode

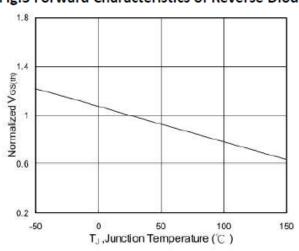


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

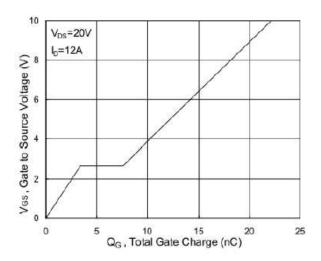


Fig.4 Gate-Charge Characteristics

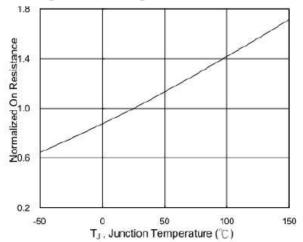
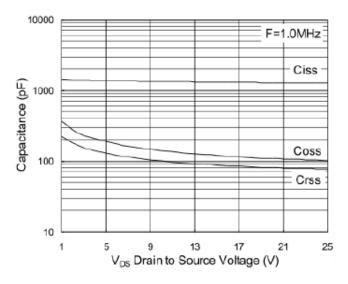


Fig.6 Normalized RDSON vs. TJ



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted



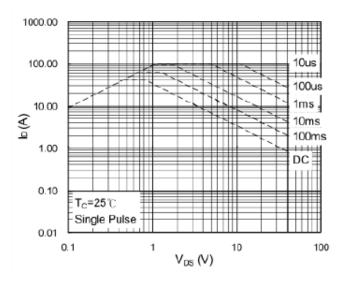


Fig.7 Capacitance

Fig.8 Safe Operating Area

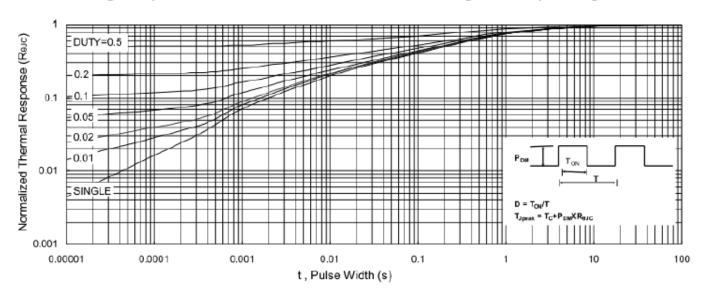


Fig.9 Normalized Maximum Transient Thermal Impedance



Figure A: Gate Charge Test Circuit and Waveform

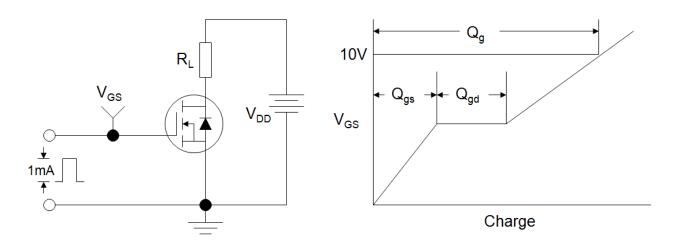


Figure B: Resistive Switching Test Circuit and Waveform

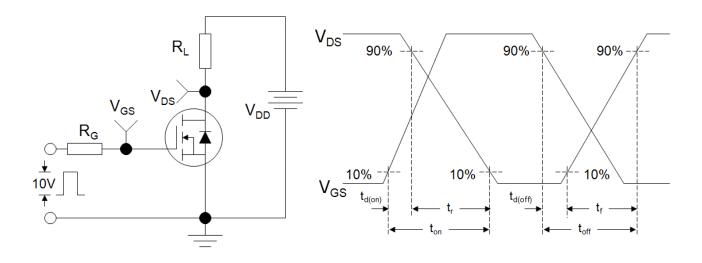
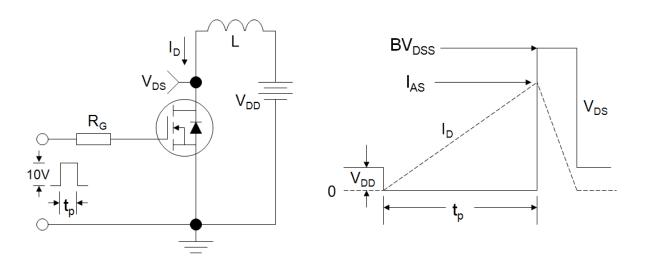
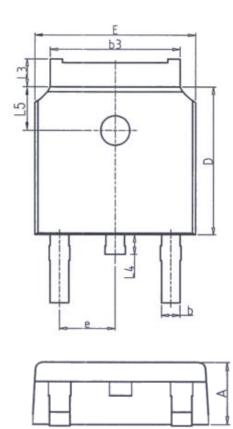


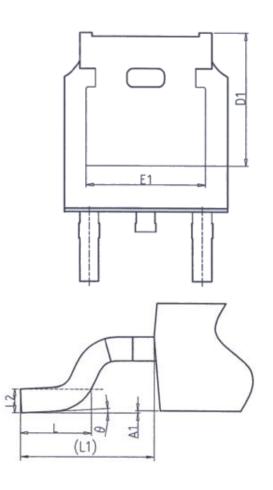
Figure C: Unclamped Inductive Switching Test Circuit and Waveform





TO-252





Unit: mm				
Symbol	Min.	Max.		
Α	2. 20	2. 40		
A1	0.00	0. 20		
A2	0. 97	1.17		
b	0. 68	0. 90		
b3	5. 20	5. 50		
С	0. 43	0. 63		
D	5. 98	6. 22		
D1	5. 30REF			
E	6. 40	6. 80		
E1	4. 63	_		

Unit: mm				
Symbol	Min. Max.			
е	2. 286BSC			
Н	9. 40	10.50		
L	1. 38	1. 75		
L1	2. 90REF			
L2	0. 51BSC			
L3	0.88	1. 28		
L4	_	1.00		
L5	1. 65	1. 95		
θ	0°	8°		



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